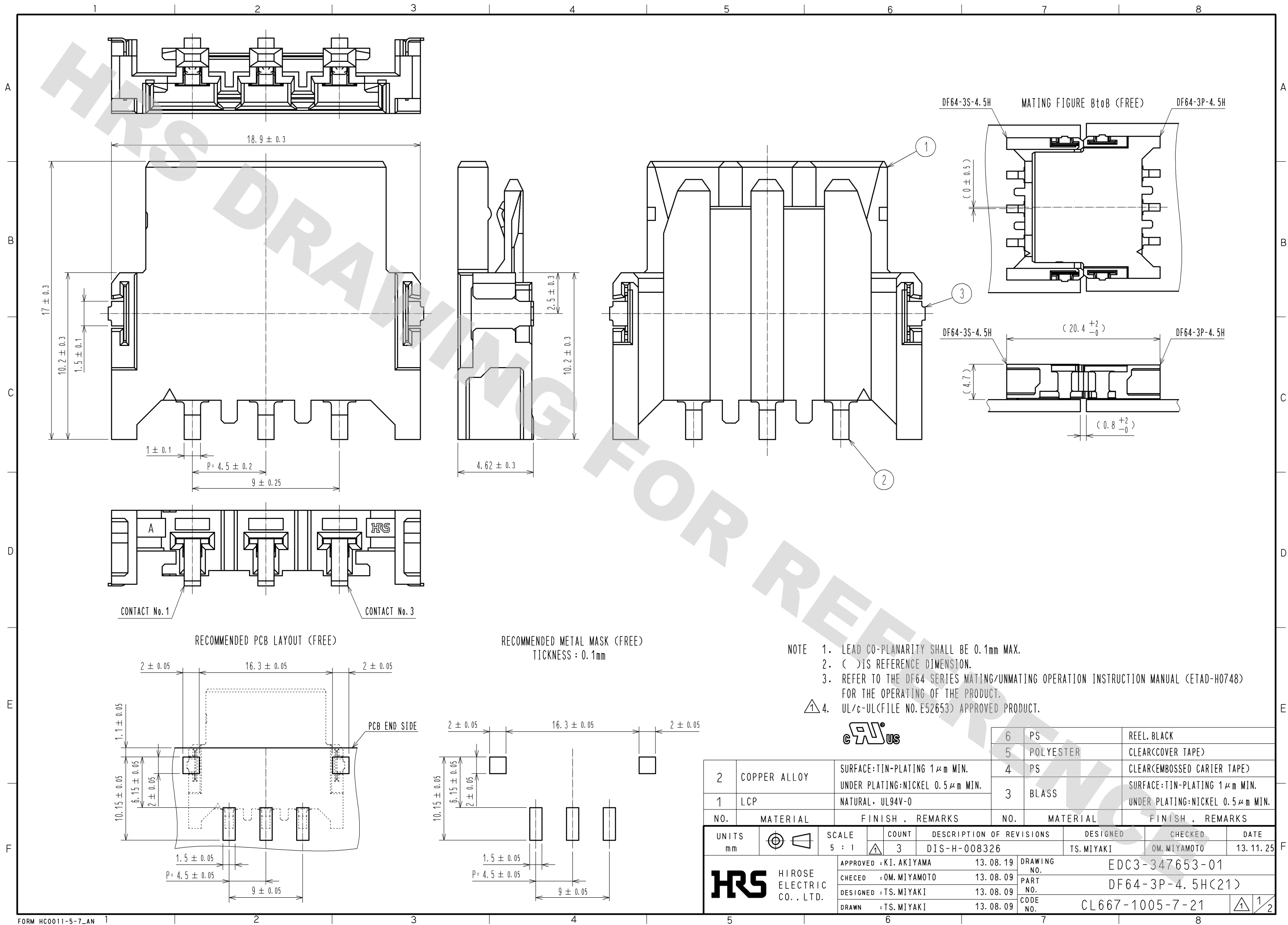
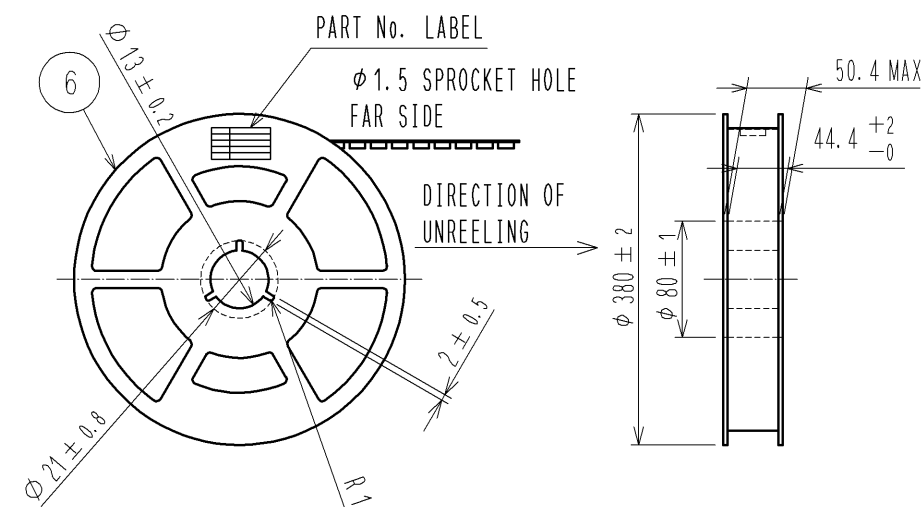
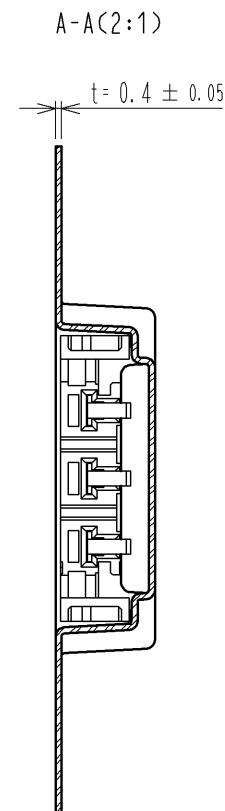
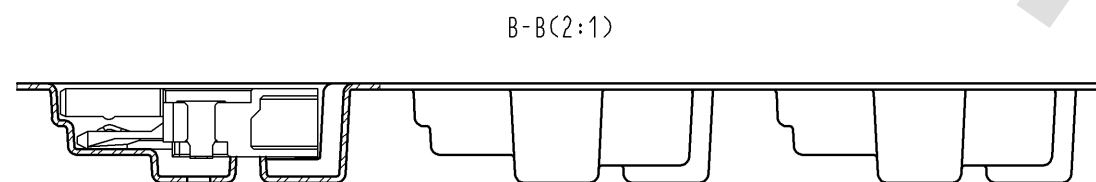






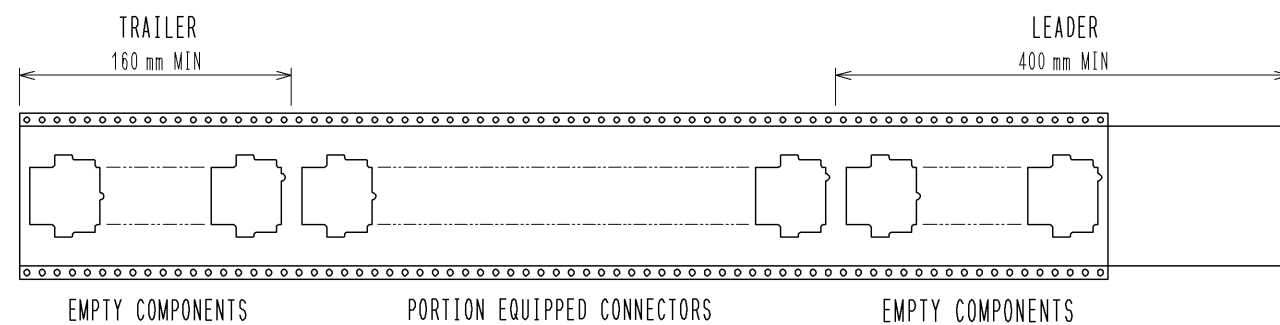
DETAIL OF PART No. LABEL

|      |                  |
|------|------------------|
| 生産月日 | 年 月 日            |
| 図 番  | CL667-1005-7-21  |
| 品 名  | DF64-3P-4.5H(21) |
| 納入数量 | 500 K0           |
| 納入者  | ヒロセ電機(株)         |



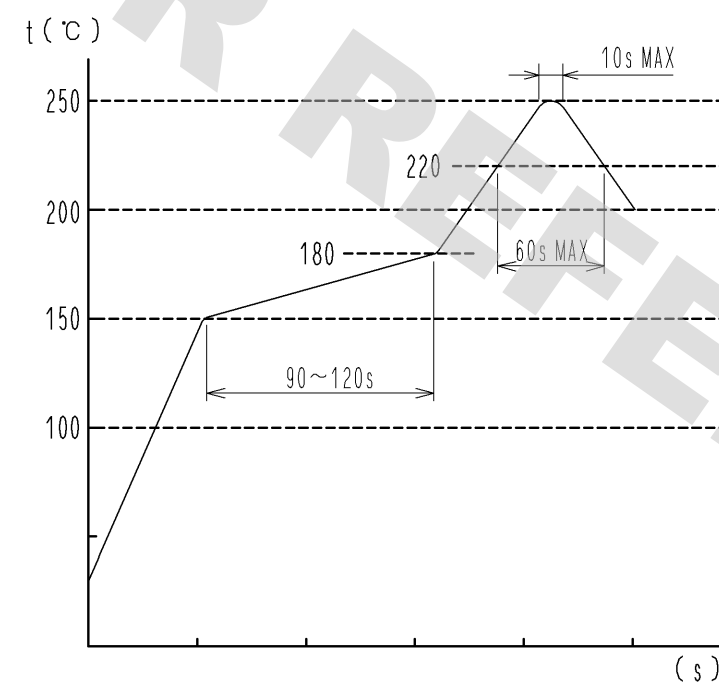
DIRECTION OF REELING 

1 6 TAPING(FREE)



△ NOTE 5. 1 REEL:500 CONNECTORS.  
 6 REEL TO JIS C 0806.(PACKAGING OF COMPONENTS FOR AUTOMATING HANDLING)  
 7. ( ) IS REFERENCE DIMENSION.

REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES 2 CYCLES MAX  
THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART.  
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE,  
PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT  
THE PROFILE.  
THEREFOR, A THOROUGH EVALUATION OF MOUNTING CONDITION IS  
REQUIRED PRIOR TO PRODUCTION.  
TEMPERATURE IS MEASURED AT CONTACT LEAD.